

特征/Features	外形尺寸/Outline Dimensions			
<ul style="list-style-type: none"> ◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V 	Case: GBU Series Dimensions in millimeters			序号 Min(mm) MAX(mm)
				A
B				
C				
D				
E				
F				
G				
H				
I				
J				
K				
L				
M				
机械参数/Machanical Data				
<ul style="list-style-type: none"> ◆ 本体：塑封 Case: plastic package ◆ 标识/极性：本体标记 Marking / Polarity: Marked on Body ◆ 重量：约克 Weight: About 3.85grams 				

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

符号 Symbol	特性 Characteristic	GBU8							单位 Unit
		005	01	02	04	06	08	10	
V _{RRM}	最大反向重复峰值电压 Maxmum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
I _{F(AV)}	平均整流输出电流 Average Forward Output Rectified Current@Ta=120°C	8							A
V _F	正向峰值电压 Forward Voltage Per Leg @I _{FM} =8.0A	1.03							V
I _{FSM}	正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load	180							A
I _R	反向漏电流 Maximum DC reverse current at rated DC blocking voltage per leg	5 500							uA
i ² t	热容值 Rating for fusing (t<8.3ms)	134							A ² S
V _{isol}	绝缘耐压 Rms isolation voltage from case to leads	2500							V
C _J	典型结电容 Typical Junction Capacitance	50							pF
R _{θJC}	热阻 Maximum thermal resistance per leg	2							°C/W
T _j , T _{STG}	结温， 存储条件 Operating Junction and storage temperature range	-55~150							°C

Note:
 (1) Junction to case with heatsink
 (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .

◆ 特性曲线 (典型) **Characteristics(Typical)**

Fig 1-forwardCurrent derating Curve
图1正向电流降额曲线

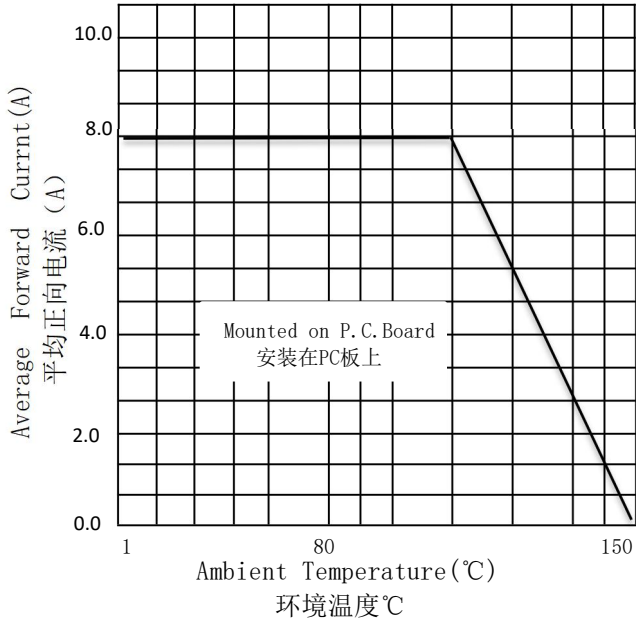


Fig.2-Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

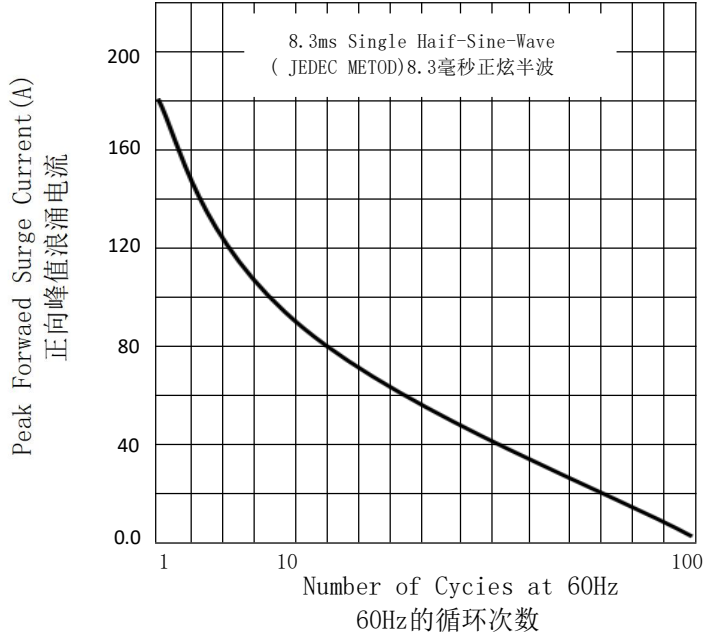


Fig.3-Typical Reverse Characteristics
图3. 典型的反向特性

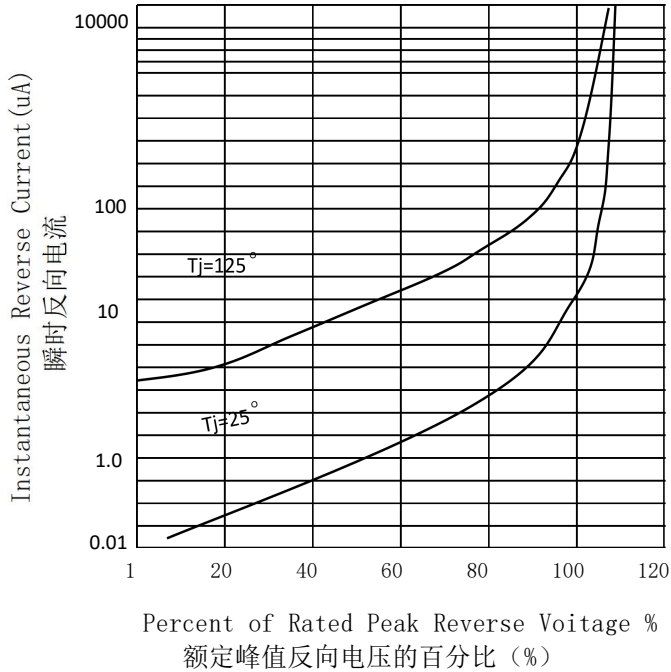


Fig.4-Typical Forward Characteristics
图4. 典型的正向特性

